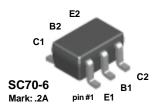


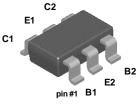
# FFB3906

# FMB3906

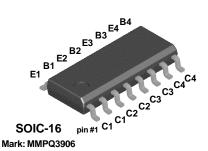
# **MMPQ3906**



NOTE: The pinouts are symmetrical; pin 1 and pin 4 are interchangeable. Units inside the carrier can be of either orientation and will not affect the functionality of the device.







# **PNP Multi-Chip General Purpose Amplifier**

This device is designed for general purpose amplifier and switching applications at collector currents of 10 µA to 100 mA. Sourced from Process 66.

## **Absolute Maximum Ratings\***

T<sub>A</sub> = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
V <sub>CEO</sub>	Collector-Emitter Voltage	40	V
V <sub>CBO</sub>	Collector-Base Voltage	40	V
V <sub>EBO</sub>	Emitter-Base Voltage	5.0	V
I <sub>C</sub>	Collector Current - Continuous	200	mA
T <sub>J</sub> , T <sub>stg</sub>	Operating and Storage Junction Temperature Range	-55 to +150	°C

<sup>\*</sup>These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

#### **Thermal Characteristics**

T<sub>A</sub> = 25°C unless otherwise noted

Symbol	Characteristic	Max			Units
		FFB3904	FMB3904	MMPQ3904	
P <sub>D</sub>	Total Device Dissipation Derate above 25°C	300 2.4	700 5.6	1,000 8.0	mW mW/°C
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient Effective 4 Die Each Die	415	180	125 240	°C/W °C/W °C/W

NOTES:

1) These ratings are based on a maximum junction temperature of 150 degrees C.

2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

(continued)

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T<sub>A</sub> = 25°C unless otherwise noted

OFF CHARACTE	RISTICS				
V <sub>(BR)CEO</sub> Collective Voltage	ctor-Emitter Breakdown ge*	$I_C = 1.0 \text{ mA}, I_B = 0$	40		V
V <sub>(BR)CBO</sub> Collect	ctor-Base Breakdown Voltage	$I_C = 10 \mu\text{A}, \ I_E = 0$	40		V
V <sub>(BR)EBO</sub> Emitte	er-Base Breakdown Voltage	$I_E = 10  \mu A,  I_C = 0$	5.0		V
I <sub>BL</sub> Base	Cutoff Current	V <sub>CE</sub> = 30 V, V <sub>BE</sub> = 3.0 V		50	nA
I <sub>CEX</sub> Collect	ctor Cutoff Current	V <sub>CE</sub> = 30 V, V <sub>BE</sub> = 3.0 V		50	nA

h <sub>FE</sub>	DC Current Gain *	$I_C = 0.1 \text{ mA}, V_{CE} = 1.0 \text{ V}$	60		
		$I_C = 1.0 \text{ mA}, V_{CE} = 1.0 \text{ V}$	80		
		$I_C = 10 \text{ mA}, V_{CE} = 1.0 \text{ V}$	100	300	
		$I_C = 50 \text{ mA}, V_{CE} = 1.0 \text{ V}$	60		
		$I_C = 100 \text{ mA}, V_{CE} = 1.0 \text{ V}$	30		
V <sub>CE(sat)</sub>	Collector-Emitter Saturation Voltage	$I_C = 10 \text{ mA}, I_B = 1.0 \text{ mA}$		0.25	V
. ,	_	$I_C = 50 \text{ mA}, I_B = 5.0 \text{ mA}$		0.4	V
V <sub>BE(sat)</sub>	Base-Emitter Saturation Voltage	$I_C = 10 \text{ mA}, I_B = 1.0 \text{ mA}$	0.65	0.85	V
		$I_C = 50 \text{ mA}, I_B = 5.0 \text{ mA}$		0.95	V

## SMALL SIGNAL CHARACTERISTICS

f <sub>T</sub>	Current Gain - Bandwidth Product	$I_C = 10 \text{ mA}, V_{CE} = 20 \text{ V},$ f = 100 MHz	450	MHz
C <sub>obo</sub>	Output Capacitance	$V_{CB} = 5.0 \text{ V}, I_E = 0,$ f = 100 kHz	3.0	pF
C <sub>ibo</sub>	Input Capacitance	$V_{EB} = 0.5 \text{ V}, I_{C} = 0,$ f = 100 kHz	8.0	pF
NF	Noise Figure (except MMPQ3906)	$I_C = 100 \mu A, V_{CE} = 5.0 V,$	2.5	dB
		$R_S = 1.0 k\Omega$ , $f=10$ Hz to 15.7 kHz		

#### **SWITCHING CHARACTERISTICS**

t <sub>d</sub>	Delay Time	$V_{CC} = 3.0 \text{ V}, V_{BE} = 0.5 \text{ V},$	15	ns
t <sub>r</sub>	Rise Time	$I_C = 10 \text{ mA}, I_{B1} = 1.0 \text{ mA}$	20	ns
ts	Storage Time	V <sub>CC</sub> = 3.0 V, I <sub>C</sub> = 10mA	110	ns
t <sub>f</sub>	Fall Time	$I_{B1} = I_{B2} = 1.0 \text{ mA}$	40	ns

<sup>\*</sup>Pulse Test: Pulse Width  $\leq$  300  $\mu$ s, Duty Cycle  $\leq$  2.0%

## **Spice Model**

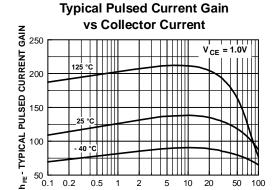
PNP (Is=1.41f Xti=3 Eg=1.11 Vaf=18.7 Bf=180.7 Ne=1.5 Ise=0 Ikf=80m Xtb=1.5 Br=4.977 Nc=2 Isc=0 Ikr=0 Rc=2.5 Cjc=9.728p Mjc=.5776 Vjc=.75 Fc=.5 Cje=8.063p Mje=.3677 Vje=.75 Tr=33.42n Tf=179.3p Itf=.4 Vtf=4 Xtf=6 Rb=10)

(continued)

## **Typical Characteristics**

0.5

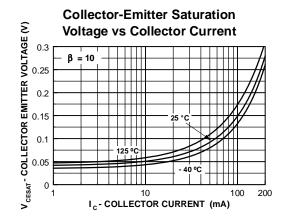
50 L 0.1 0.2

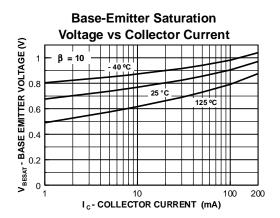


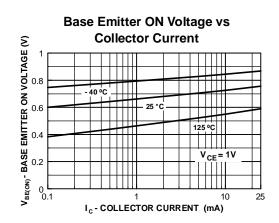
2

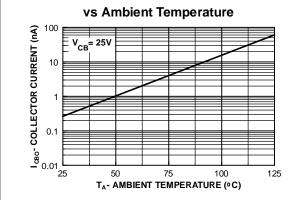
I<sub>c</sub> - COLLECTOR CURRENT (mA)

5 10 20 50

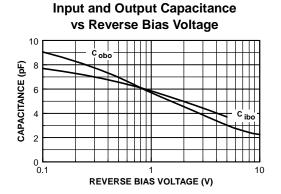








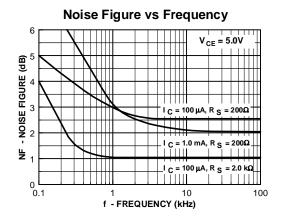
**Collector-Cutoff Current** 

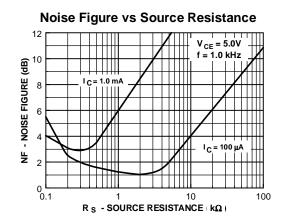


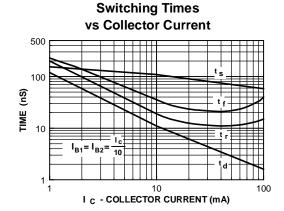
**Common-Base Open Circuit** 

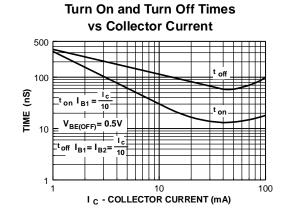
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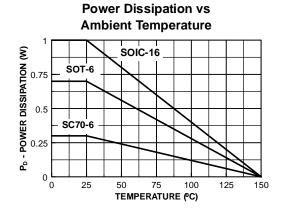
## Typical Characteristics (continued)





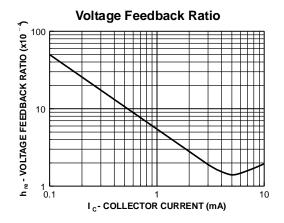


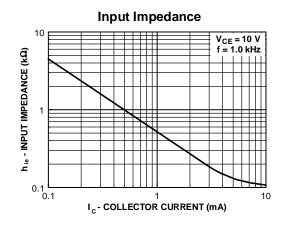


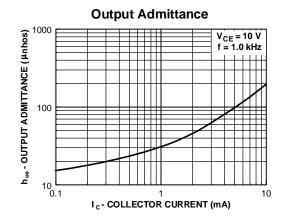


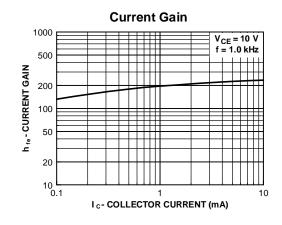
(continued)

# Typical Characteristics (continued)









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FACT<sup>TM</sup> QS<sup>TM</sup>

 $\begin{array}{lll} \mathsf{FACT} \ \mathsf{Quiet} \ \mathsf{Series^{\mathsf{TM}}} & \mathsf{Quiet} \ \mathsf{Series^{\mathsf{TM}}} \\ \mathsf{FAST}^{\circledast} & \mathsf{Super} \mathsf{SOT^{\mathsf{TM}}}\text{--3} \\ \mathsf{FASTr^{\mathsf{TM}}} & \mathsf{Super} \mathsf{SOT^{\mathsf{TM}}}\text{--6} \\ \mathsf{GTO^{\mathsf{TM}}} & \mathsf{Super} \mathsf{SOT^{\mathsf{TM}}}\text{--8} \\ \mathsf{Hi} \mathsf{SeC^{\mathsf{TM}}} & \mathsf{TinyLogic^{\mathsf{TM}}} \\ \end{array}$ 

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